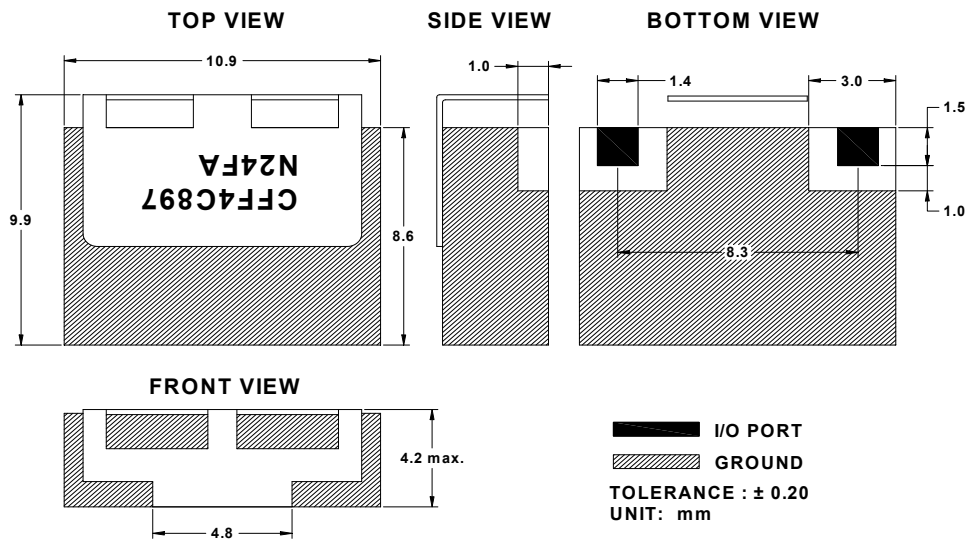


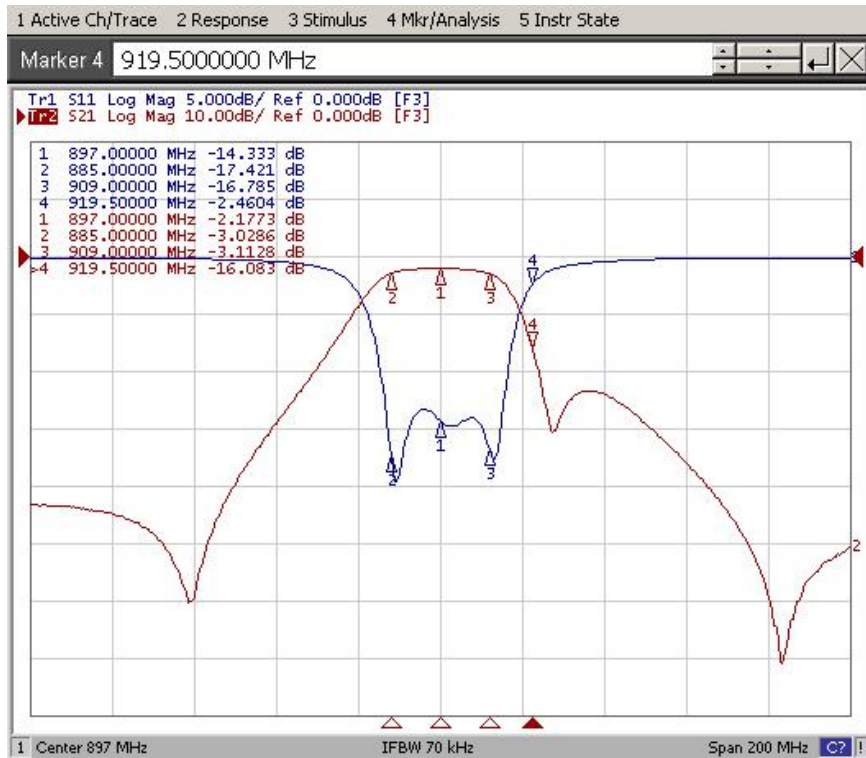
**Electrical Specification**

| ITEMS  | SPEC                       | UNIT   |
|--|----------------------------|--------|
| Center Frequency [fo]  | 897.0                      | MHz    |
| Bandwidth [BW]   | $f_o \pm 12$ [ 885 ~ 909 ] | MHz    |
| Insertion Loss in BW   | 3.5                        | dB max |
| Ripple in BW   | 1.5                        | dB max |
| Return Loss in BW  | 10.0                       | dB min |
| Attenuation<br><input checked="" type="checkbox"/> Absolute Value<br><input type="checkbox"/> Relative Value | 15 dB min. @ 919.5 MHz     | MHz    |
|  | dB min @ $f_o \pm$ [ & ]   | MHz    |
|  | dB min @ $f_o \pm$ [ & ]   | MHz    |
|  | dB min @ $f_o \pm$ [ ~ ]   | MHz    |
| Group Delay Variation  |                            | ns max |
| Input Power  | 2                          | W max. |
| In/Out Impedance   | 50 $\Omega$                |        |
| Operation Temperature Range  | -40°C to +85°C             |        |

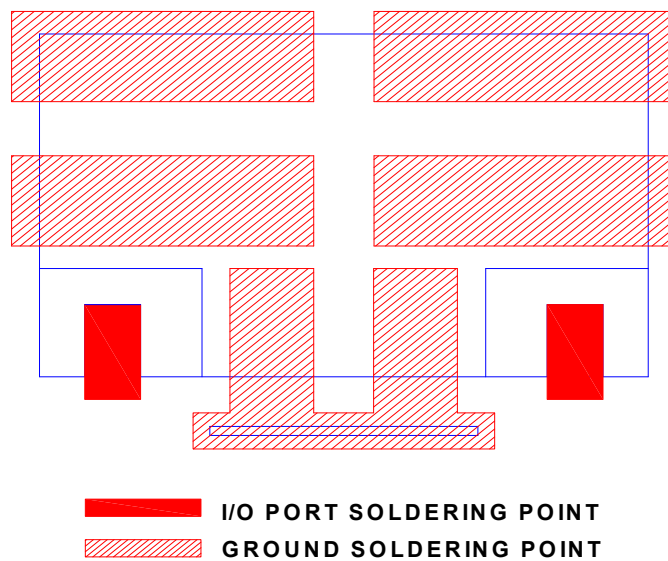
**Mechanical Specification**



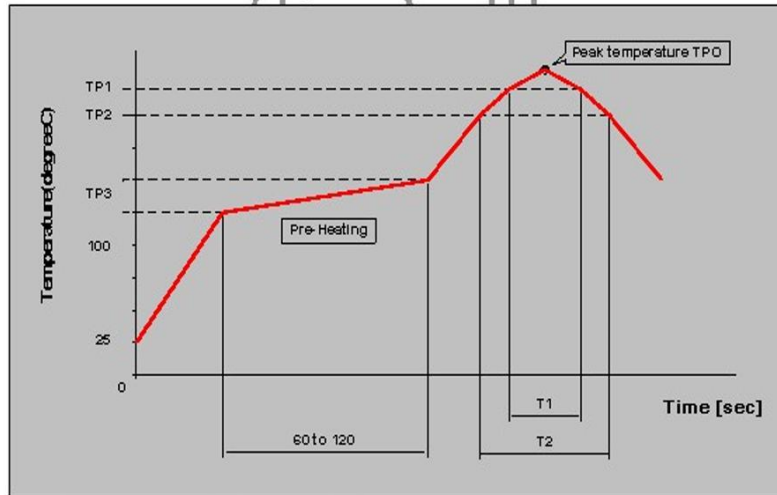
 Plot Data



 Recommended PC Board Pattern



**Soldering Condition**



Measuring point of temperature : IN-OUT Terminals of The Device

Reflow Soldering : Both Convection and Infrared Rays, Hot Air and Hot Plate

| Reflow standard condition                | TP0 (°C) | TP1 (°C) | T1 (s)   | TP2 (°C) | T2 (s) | TP3 (°C)   |
|--|----------|----------|----------|----------|--------|------------|
| Sn-3Ag-0.5 solder                        | 245+/-5  | 220      | 30 to 60 | —        | —      | 150 to 180 |
| Test condition of reflow heat resistance | 260+5/-0 | 240      | 20       | 220      | 70     | 150 to 180 |